

Silicon PIN Photodiode



DESCRIPTION

VEMD11940FX01 is a high speed and high sensitive PIN photodiode in a miniature side looking, surface mount package (SMD) with daylight blocking filter. Filter is matched with IR emitters operating at wavelength of 830 nm to 950 nm. The photo sensitive area of the chip is 0.053 mm².

FEATURES

Package type: Surface mount

· Package form: Side view

• Dimensions (L x W x H in mm): 3 x 2 x 0.6

AEC-Q101 qualified

· High radiant sensitivity

· Daylight blocking filter matched with 830 nm to 950 nm IR emitters

• Angle of half sensitivity: $\varphi = \pm 75^{\circ}$

matched Package with emitter VSMB11940X01

• Floor life: 168 h, MSL 3, according to J-STD-020

Lead (Pb)-free reflow soldering

· Material categorization: For definitions of compliance please see www.vishav.com/doc?99912



(5-2008)

AUTOMOTIVE

APPLICATIONS

- · High speed photo detector
- · Infrared remote control
- · Infrared data transmission
- Photo interrupters
- IR touch panels

PRODUCT SUMMARY				
COMPONENT	I _{ra} (μΑ)	φ (deg)	λ _{0.5} (nm)	
VEMD11940FX01	1.13	± 75	780 to 1050	

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VEMD11940FX01	Tape and reel	MOQ: 4000 pcs, 4000 pcs/reel	Side view	

Note

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	60	V
Power dissipation	T _{amb} ≤ 25 °C	P _V	104	mW
Junction temperature		T _j	100	°C
Operating temperature range		T _{amb}	-40 to +100	°C
Storage temperature range		T _{stg}	-40 to +100	°C
Soldering temperature	Acc. reflow solder profile fig. 8	T _{sd}	260	°C
Thermal resistance junction/ambient	Acc. J-STD-051	R _{thJA}	580	K/W

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 50 mA	V _F		1.7		V
Breakdown voltage	$I_R = 100 \mu A, E = 0$	$V_{(BR)}$	32			V
Reverse dark current	V _R = 10 V, E = 0	I _{ro}		< 1	10	nA
Diode capacitance	V _R = 0 V, f = 1 MHz, E = 0	C _D		1.1		pF
	V _R = 3 V, f = 1 MHz, E = 0	C _D		0.5		pF
Open circuit voltage	$E_{e} = 1 \text{ mW/cm}^{2}, \lambda = 950 \text{ nm}$	Vo		350		mV
Temperature coefficient of Vo	$E_{e} = 1 \text{ mW/cm}^{2}, \lambda = 950 \text{ nm}$	TK _{Vo}		-2.7		mV/K
Short circuit current	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	l _k		1.13		μΑ
Temperature coefficient of I _k	$E_{e} = 1 \text{ mW/cm}^{2}, \lambda = 950 \text{ nm}$	TK _{lk}		0.1		%/K
Reverse light current	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 950 \text{ nm}$, $V_R = 5 \text{ V}$	I _{ra}	0.8	1.13	1.8	μΑ
Angle of half sensitivity		φ		± 75		deg
Wavelength of peak sensitivity		λ_{p}		950		nm
Range of spectral bandwidth		λ _{0.5}		780 to 1050		nm
Rise time	$V_R = 10 \text{ V}, R_L = 1 \text{ k}\Omega, \lambda = 820 \text{ nm}$	t _r		1000		ns
Fall time	$V_R = 10 \text{ V}, R_L = 1 \text{ k}\Omega, \lambda = 820 \text{ nm}$	t _f		1000		ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

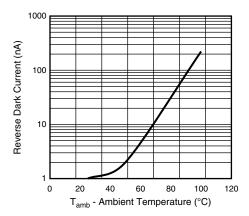


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

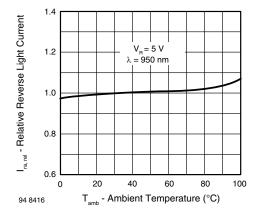


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

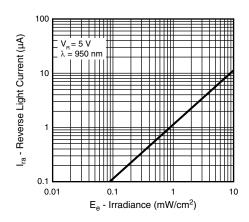


Fig. 3 - Reverse Light Current vs. Irradiance

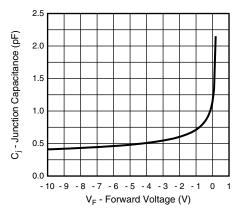


Fig. 4 - Diode Capacitance vs. Reverse Voltage



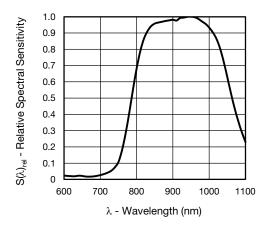


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

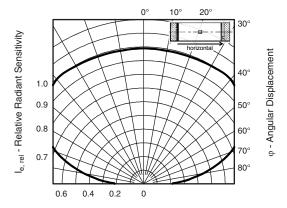


Fig. 6 - Relative Radiant Sensitivity vs. Angular Displacement - Horizontal

REFLOW SOLDER PROFILE

255 - 260 °C 217 °C 3 °C/SEC. MAX. 200 °C 150 °C 3 °C/SEC. MAX. 6 °C/SEC. MAX.

Fig. 8 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020D

TIME

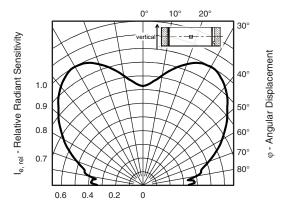


Fig. 7 - Relative Radiant Sensitivity vs. Angular Displacement - Vertical

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

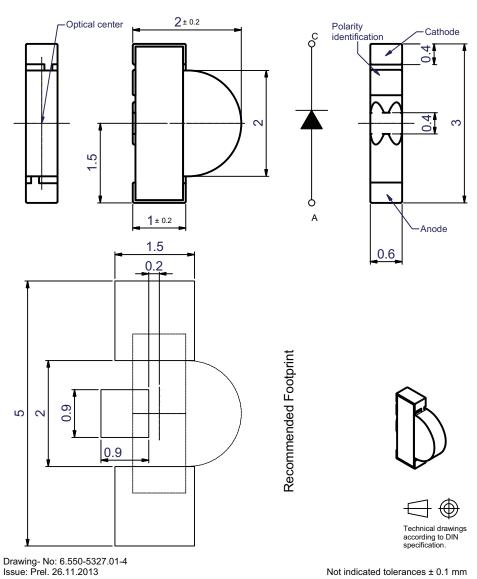
Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 3, acc. to J-STD-020.

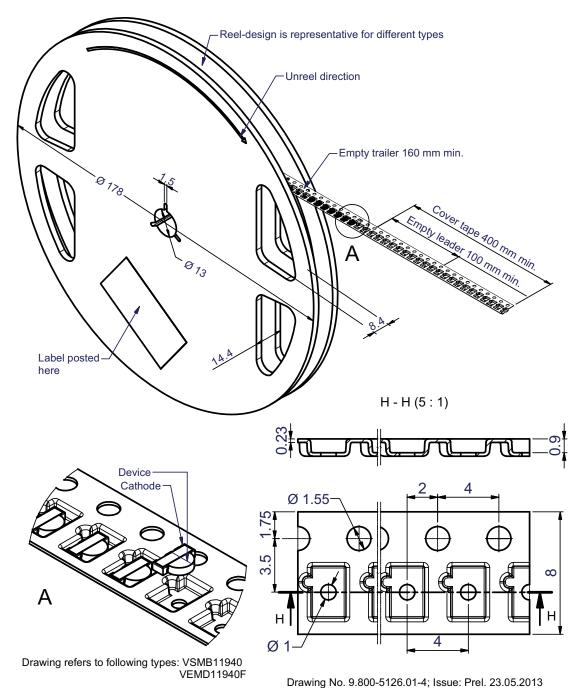
DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.

PACKAGE DIMENSIONS in millimeters



TAPING AND REEL DIMENSIONS in millimeters





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Vishay

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